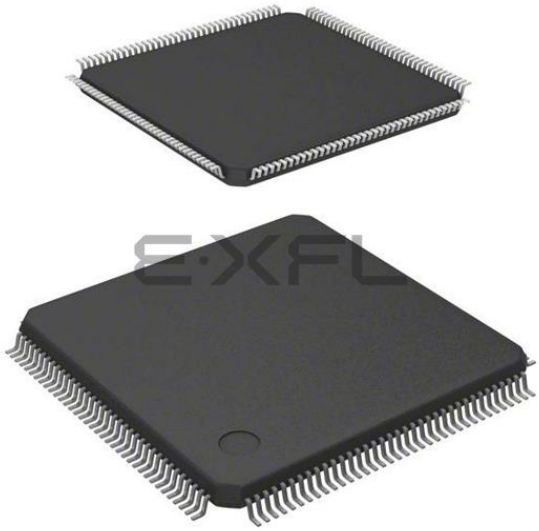

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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	e200z0h
Core Size	32-Bit Single-Core
Speed	64MHz
Connectivity	CANbus, LINbus, SPI, UART/USART
Peripherals	DMA, POR, PWM, WDT
Number of I/O	80
Program Memory Size	1MB (1M x 8)
Program Memory Type	FLASH
EEPROM Size	64K x 8
RAM Size	80K x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 5.5V
Data Converters	A/D 26x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	144-LQFP
Supplier Device Package	144-LQFP (20x20)
Purchase URL	https://www.e-xfl.com/product-detail/stmicroelectronics/spc56ap60l5befay

SPC56xP54x/SPC56xP60x is present on the market in two different options enabling different features: Full-featured, and Airbag configuration. *Table 3* shows the main differences between the two versions.

Table 3. SPC56xP54x/SPC56xP60x device configuration difference

Feature	Enhanced Full-featured	Full-featured	Airbag
FlexCAN (controller area network)	3	2	2
CTU (cross triggering unit)	Yes		No
FlexRay	Yes (64 message buffer)		No
DSPI (deserial serial peripheral interface) modules	5		4
CRC (cyclic redundancy check) unit	2		1

1.4 Block diagram

Figure 1 shows a top-level block diagram of the SPC56xP54x/SPC56xP60x MCU. *Table 4* summarizes the functions of the blocks.

Table 4. SPC56xP54x/SPC56xP60x series block summary (continued)

Block	Function
Peripheral bridge (PBRIDGE)	Is the interface between the system bus and on-chip peripherals
Periodic interrupt timer (PIT)	Produces periodic interrupts and triggers
Power control unit (MC_PCU)	Reduces the overall power consumption by disconnecting parts of the device from the power supply via a power switching device; device components are grouped into sections called “power domains” which are controlled by the PCU
Reset generation module (MC_RGM)	Centralizes reset sources and manages the device reset sequence of the device
Semaphore unit (SEMA4)	Provides the hardware support needed in multi-core systems for implementing semaphores and provide a simple mechanism to achieve lock/unlock operations via a single write access
Static random-access memory (SRAM)	Provides storage for program code, constants, and variables
System integration unit lite (SIUL)	Provides control over all the electrical pad controls and up 32 ports with 16 bits of bidirectional, general-purpose input and output signals and supports up to 32 external interrupts with trigger event configuration
System status and configuration module (SSCM)	Provides system configuration and status data (such as memory size and status, device mode and security status), device identification data, debug status port enable and selection, and bus and peripheral abort enable/disable
System timer module (STM)	Provides a set of output compare events to support AUTOSAR(1) and operating system tasks
System watchdog timer (SWT)	Provides protection from runaway code
Wakeup unit (WKPU)	Supports up to 18 external sources that can generate interrupts or wakeup events, of which 1 can cause non-maskable interrupt requests or wakeup events.

1. AUTOSAR: AUTomotive Open System ARchitecture (see autosar.org web site).

1.5 Feature details

1.5.1 High performance e200z0h core processor

The e200z0h Power Architecture core provides the following features:

- High performance e200z0 core processor for managing peripherals and interrupts
- Single issue 4-stage pipeline in-order execution 32-bit Power Architecture CPU
- Harvard architecture
- Variable length encoding (VLE), allowing mixed 16-bit and 32-bit instructions
  - Results in smaller code size footprint
  - Minimizes impact on performance
- Branch processing acceleration using lookahead instruction buffer
- Load/store unit
  - 1-cycle load latency
  - Misaligned access support
  - No load-to-use pipeline bubbles
- Thirty-two 32-bit general purpose registers (GPRs)
- Separate instruction bus and load/store bus Harvard architecture
- Hardware vectored interrupt support
- Reservation instructions for implementing read-modify-write constructs
- Long cycle time instructions, except for guarded loads, do not increase interrupt latency
- Extensive system development support through Nexus debug port
- Non maskable Interrupt support

1.5.2 Crossbar switch (XBAR)

The XBAR multi-port crossbar switch supports simultaneous connections between six master ports and six slave ports. The crossbar supports a 32-bit address bus width and a 32-bit data bus width.

The crossbar allows for two concurrent transactions to occur from any master port to any slave port; but one of those transfers must be an instruction fetch from internal flash memory. If a slave port is simultaneously requested by more than one master port, arbitration logic selects the higher priority master and grant it ownership of the slave port. All other masters requesting that slave port are stalled until the higher priority master completes its transactions. Requesting masters are treated with equal priority and will be granted access to a slave port in round-robin fashion, based upon the ID of the last master to be granted access.

Table 5. Supply pins (continued)

Supply		Pin		
Symbol	Description	LQFP 100	LQFP 144	LQFP 176[1]
$V_{SS\_LV\_COR0}$	1.2 V Decoupling pins for core logic GND. Decoupling capacitor must be connected between these pins and the nearest $V_{DD\_LV\_COR0}$ pin.	11	17	25
$V_{DD\_LV\_COR1}$	1.2 V Decoupling pins for core logic supply. Decoupling capacitor must be connected between these pins and the nearest $V_{SS\_LV\_COR1}$ pin.	65	93	117
$V_{SS\_LV\_COR1}$	1.2 V Decoupling pins for core logic GND. Decoupling capacitor must be connected between these pins and the nearest $V_{DD\_LV\_COR1}$ pin.	66	94	118
$V_{DD\_LV\_COR2}$	1.2 V Decoupling pins for core logic supply. Decoupling capacitor must be connected between these pins and the nearest $V_{SS\_LV\_COR2}$ pin.	92	131	155
$V_{SS\_LV\_COR2}$	1.2 V Decoupling pins for core logic GND. Decoupling capacitor must be connected between these pins and the nearest $V_{DD\_LV\_COR\ 2}$ pin.	93	132	156
$V_{DD\_LV\_COR3}$	1.2 V Decoupling pins for core logic supply. Decoupling capacitor must be connected between these pins and the nearest $V_{SS\_LV\_COR3}$ pin.	25	36	44
$V_{SS\_LV\_COR3}$	1.2 V Decoupling pins for core logic GND. Decoupling capacitor must be connected between these pins and the nearest $V_{DD\_LV\_COR\ 3}$ pin.	24	35	43

1. LQFP176 available only as development package.
2. See datasheet Voltage Regulator Electrical Characteristics section for more details.

2.2.2 System pins

Table 6 and *Table 7* contain information on pin functions for the SPC56xP54x/SPC56xP60x devices. The pins listed in *Table 6* are single-function pins. The pins shown in *Table 7* are multi-function pins, programmable via their respective Pad Configuration Register (PCR) values.

Table 6. System pins

Symbol	Description	Direction	Pad Speed[1]		Pin		
			SRC=0	SRC=1	LQFP 100	LQFP 144	LQFP 176[2]
Dedicated pins							
MDO0	Nexus Message Data Output—line 0	Output Only	Fast		—	9	17
MDO4	Nexus Message Data Output—line 4	Output Only	Fast		—	—	7

Table 6. System pins (continued)

Symbol	Description	Direction	Pad Speed[1]		Pin		
			SRC=0	SRC=1	LQFP 100	LQFP 144	LQFP 176[2]
MDO5	Nexus Message Data Output—line 5	Output Only	Fast		—	—	8
MDO6	Nexus Message Data Output—line 6	Output Only	Fast		—	—	9
MDO7	Nexus Message Data Output—line 7	Output Only	Fast		—	—	110
MDO8	Nexus Message Data Output—line 8	Output Only	Fast		—	—	111
MDO9	Nexus Message Data Output—line 9	Output Only	Fast		—	—	112
MDO10	Nexus Message Data Output—line 10	Output Only	Fast		—	—	166
MDO11	Nexus Message Data Output—line 11	Output Only	Fast		—	—	171
RDY	Nexus ready output	Output Only	—	—	—	—	172
NMI	Non-Maskable Interrupt	Input Only	—	—	1	1	1
XTAL	Analog output of the oscillator amplifier circuit. Needs to be grounded if oscillator is used in bypass mode.	—	—	—	18	29	37
EXTAL	Analog input of the oscillator amplifier circuit, when the oscillator is not in bypass mode. Analog input for the clock generator when the oscillator is in bypass mode.	—	—	—	19	30	38
TMS[3]	JTAG state machine control	Input Only	—	—	59	87	105
TCK[3]	JTAG clock	Input Only	—	—	60	88	106
TDI[3]	JTAG data input	Input Only	—	—	58	86	104
TDO[3]	JTAG data output	Output Only	—	—	61	89	107
Reset pin							
$\overline{\text{RESET}}$[4]	Bidirectional reset with Schmitt trigger characteristics and noise filter	Bidirectional	Medium	—	20	31	39
Test pin							
$V_{PP\ TEST}$	Pin for testing purpose only. To be tied to ground in normal operating mode.	—	—	—	74	107	131
V_{REG_BYPASS}	Pin for testing purpose only. To be tied to ground in normal operating mode.	—	—	—	34	51	59

1. SRC values refer to the value assigned to the Slew Rate Control bits of the pad configuration register.

Table 7. Pin muxing[1] (continued)

Port pin	PCR No.	Alternate function[2], [3]	Functions	Peripheral [4]	I/O direction [5]	Pad speed[6]		Pin		
						SRC = 0	SRC = 1	LQFP 100	LQFP 144	LQFP 176[7]
A[9]	PCR[9]	ALT0 ALT1 ALT2 ALT3 —	GPIO[9] CS1_2 — — SIN_4	SIUL DSPI_2 — — DSPI_4	I/O O — — I	Slow	Medium	94	134	158
A[10]	PCR[10]	ALT0 ALT1 ALT2 ALT3 —	GPIO[10] CS0_2 — — EIRQ[9]	SIUL DSPI_2 — — SIUL	I/O I/O — — I	Slow	Medium	81	118	142
A[11]	PCR[11]	ALT0 ALT1 ALT2 ALT3 —	GPIO[11] SCK_2 — — EIRQ[10]	SIUL DSPI_2 — — SIUL	I/O I/O — — I	Slow	Medium	82	120	144
A[12]	PCR[12]	ALT0 ALT1 ALT2 ALT3 —	GPIO[12] SOUT_2 — — EIRQ[11]	SIUL DSPI_2 — — SIUL	I/O O — — I	Slow	Medium	83	122	146
A[13]	PCR[13]	ALT0 ALT1 ALT2 ALT3 — —	GPIO[13] CS4_1 — — SIN_2 EIRQ[12]	SIUL DSPI_1 — — DSPI_2 SIUL	I/O O — — I I	Slow	Medium	95	136	160
A[14]	PCR[14]	ALT0 ALT1 ALT2 ALT3 —	GPIO[14] TXD ETC[4] CS5_1 EIRQ[13]	SIUL Safety Port eTimer_1 DSPI_1 SIUL	I/O O I/O O I	Slow	Medium	99	143	175
A[15]	PCR[15]	ALT0 ALT1 ALT2 ALT3 — —	GPIO[15] CS6_1 ETC[5] — RXD EIRQ[14]	SIUL DSPI_1 eTimer_1 — Safety Port SIUL	I/O O I/O — I I	Slow	Medium	100	144	176

Table 7. Pin muxing[1] (continued)

Port pin	PCR No.	Alternate function[2], [3]	Functions	Peripheral [4]	I/O direction [5]	Pad speed[6]		Pin		
						SRC = 0	SRC = 1	LQFP 100	LQFP 144	LQFP 176[7]
D[7]	PCR[55]	ALT0 ALT1 ALT2 ALT3 —	GPIO[55] CS3_1 — CS4_0 SIN_3	SIUL DSPI_1 — DSPI_0 DSPI_3	I/O O — O I	Slow	Medium	26	37	45
D[8]	PCR[56]	ALT0 ALT1 ALT2 ALT3	GPIO[56] CS2_1 RDY CS5_0	SIUL DSPI_1 nexus_0 DSPI_0	I/O O O O	Slow	Medium	21	32	40
D[9]	PCR[57]	ALT0 ALT1 ALT2 ALT3	GPIO[57] — TXD CS6_1	SIUL — LINFlex_1 DSPI_1	I/O — O O	Slow	Medium	15	26	34
D[10]	PCR[58]	ALT0 ALT1 ALT2 ALT3	GPIO[58] — CS0_3 —	SIUL — DSPI_3 —	I/O — I/O —	Slow	Medium	53	76	92
D[11]	PCR[59]	ALT0 ALT1 ALT2 ALT3	GPIO[59] — CS1_3 SCK_3	SIUL — DSPI_3 DSPI_3	I/O — O I/O	Slow	Medium	54	78	94
D[12]	PCR[60]	ALT0 ALT1 ALT2 ALT3 —	GPIO[60] — — CS7_1 RXD	SIUL — — DSPI_1 LINFlex_1	I/O — — O I	Slow	Medium	70	99	123
D[13]	PCR[61]	ALT0 ALT1 ALT2 ALT3	GPIO[61] — CS2_3 SOUT_3	SIUL — DSPI_3 DSPI_3	I/O — O O	Slow	Medium	67	95	119
D[14]	PCR[62]	ALT0 ALT1 ALT2 ALT3 —	GPIO[62] — CS3_3 — SIN_3	SIUL — DSPI_3 — DSPI_3	I/O — O — I	Slow	Medium	73	105	129
D[15]	PCR[63]	ALT0 ALT1 ALT2 ALT3 —	GPIO[63] — — — AN[20]	SIUL — — — ADC_0	Input Only	—	—	41	58	66

Table 13. Thermal characteristics for 100-pin LQFP

Symbol		Parameter	Conditions	Typical value	Unit
$R_{\theta JA}$	D	Thermal resistance junction-to-ambient, natural convection(1)	Single layer board—1s	47.3	°C/W
	D		Four layer board—2s2p	35.6	°C/W
$R_{\theta JB}$	D	Thermal resistance junction-to-board(2)	Four layer board—2s2p	19.1	°C/W
$R_{\theta JCtop}$	D	Thermal resistance junction-to-case (top)(3)	Single layer board—1s	9.1	°C/W
Ψ_{JB}	D	Junction-to-board, natural convection(4)	Operating conditions	19.1	°C/W
Ψ_{JC}	D	Junction-to-case, natural convection(5)	Operating conditions	1.1	°C/W

1. Junction-to-ambient thermal resistance determined per JEDEC JESD51-7. Thermal test board meets JEDEC specification for this package.
2. Junction-to-board thermal resistance determined per JEDEC JESD51-8. Thermal test board meets JEDEC specification for the specified package.
3. Junction-to-case at the top of the package determined using MIL-STD 883 Method 1012.1. The cold plate temperature is used for the case temperature. Reported value includes the thermal resistance of the interface layer.
4. Thermal characterization parameter indicating the temperature difference between the board and the junction temperature per JEDEC JESD51-2. When Greek letters are not available, the thermal characterization parameter is written as Psi-JB.
5. Thermal characterization parameter indicating the temperature difference between the case and the junction temperature per JEDEC JESD51-2. When Greek letters are not available, the thermal characterization parameter is written as Psi-JC.

3.5.1 General notes for specifications at maximum junction temperature

An estimation of the chip junction temperature, T_J, can be obtained from *Equation 1*:

Equation 1 $T_J = T_A + (R_{\theta JA} \times P_D)$

where:

T_A= ambient temperature for the package (^oC)

$R_{\theta JA}$= junction to ambient thermal resistance ($^oC/W$)

P_D= power dissipation in the package (W)

The junction to ambient thermal resistance is an industry standard value that provides a quick and easy estimation of thermal performance. Unfortunately, there are two values in common usage: the value determined on a single layer board and the value obtained on a board with two planes. For packages such as the PBGA, these values can be different by a factor of two. Which value is closer to the application depends on the power dissipated by other components on the board. The value obtained on a single layer board is appropriate for the tightly packed printed circuit board. The value obtained on the board with the internal planes is usually appropriate if the board has low power dissipation and the components are well separated.

When a heat sink is used, the thermal resistance is expressed in *Equation 2* as the sum of a junction to case thermal resistance and a case to ambient thermal resistance:

Equation 2 $R_{\theta JA} = R_{\theta JC} + R_{\theta CA}$

where:

$R_{\theta JA}$ = junction to ambient thermal resistance (°C/W)

$R_{\theta JC}$= junction to case thermal resistance (°C/W)

$R_{\theta CA}$= case to ambient thermal resistance (°C/W)

Figure 10. Power-up typical sequence

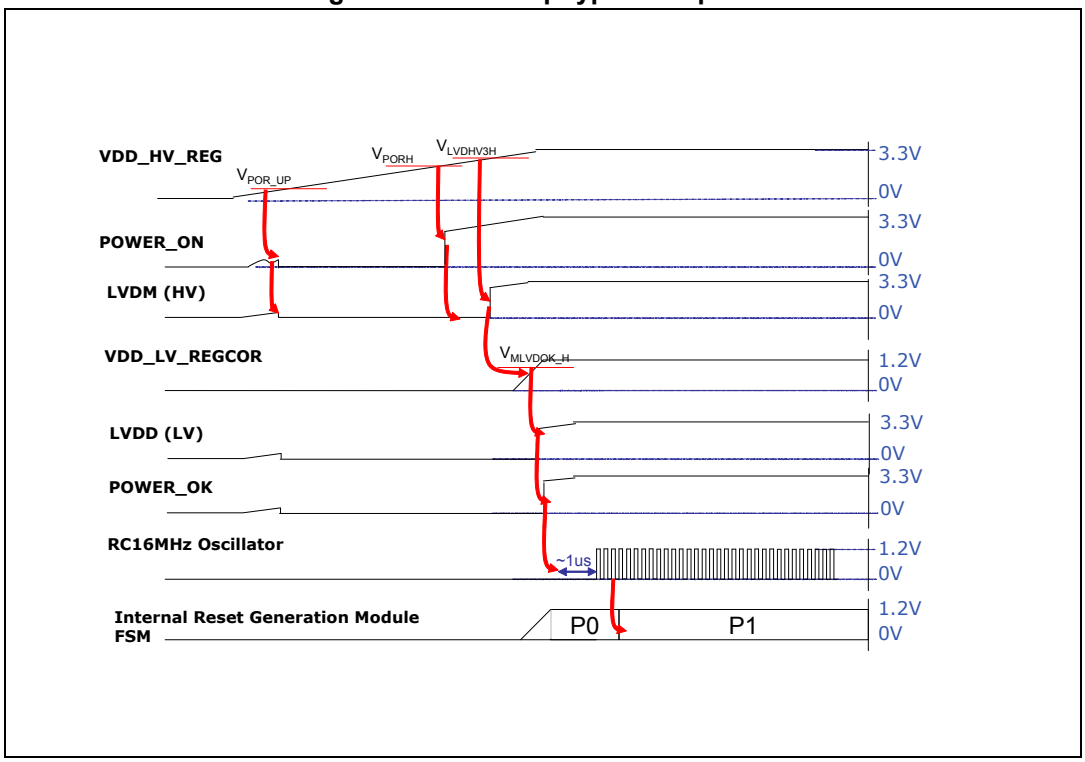


Figure 11. Power-down typical sequence

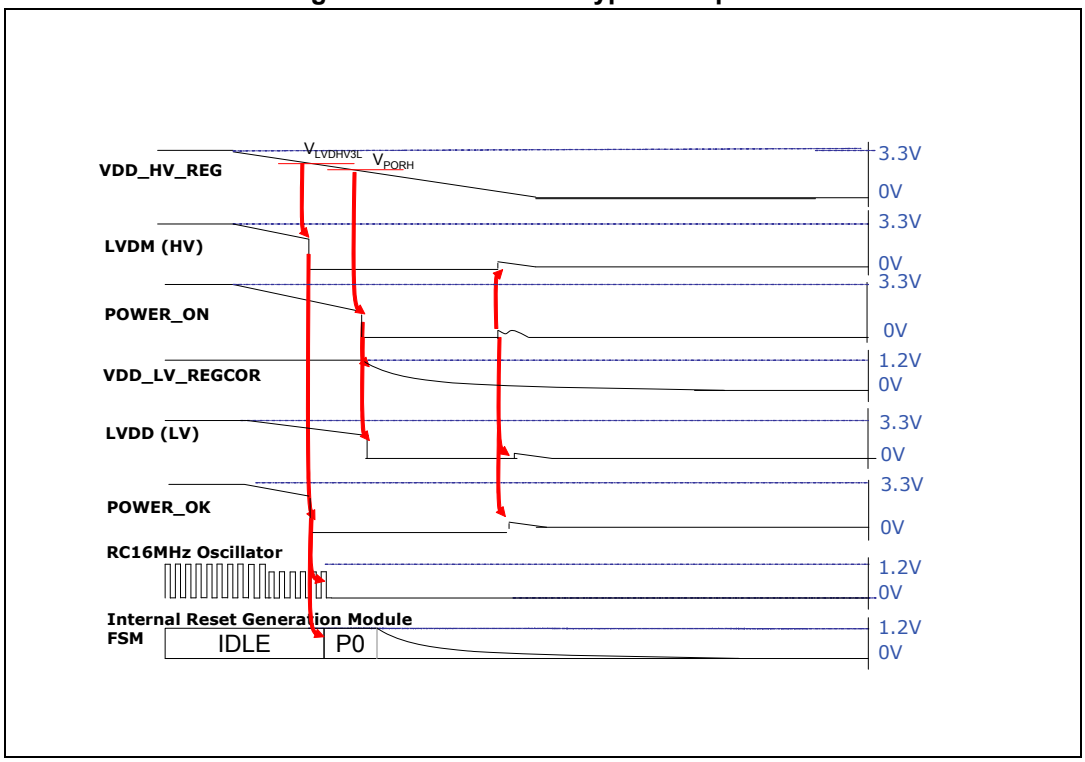
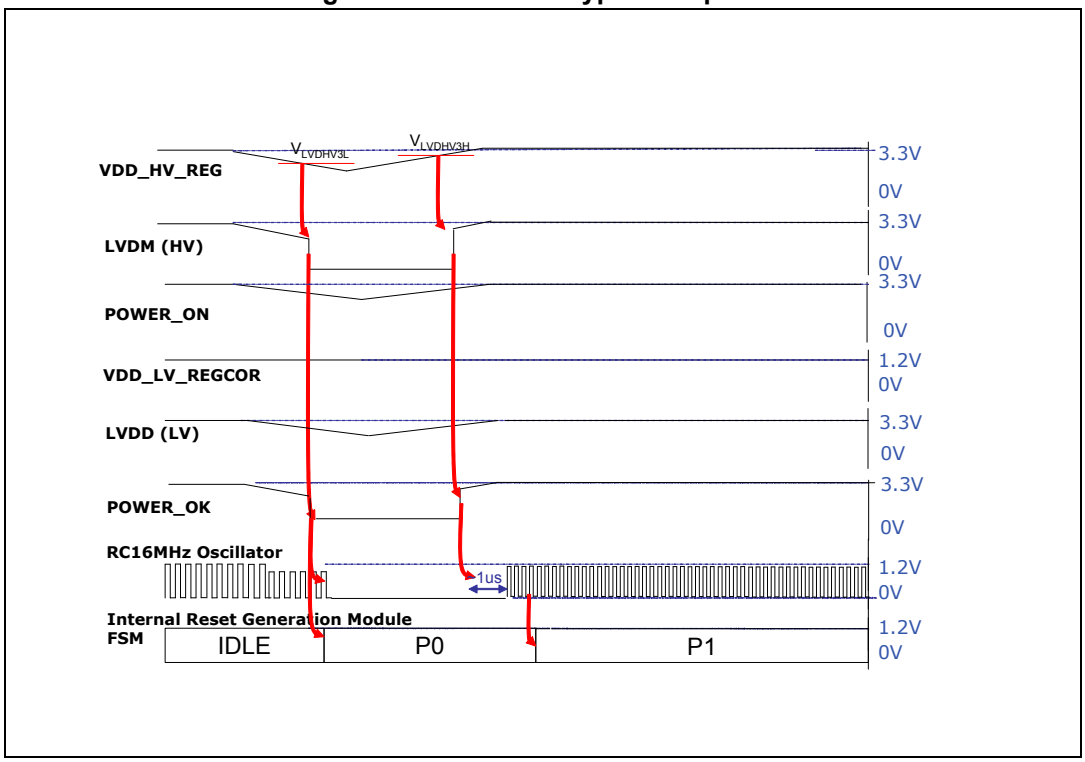


Figure 12. Brown-out typical sequence



3.10 NVUSRO register

Portions of the device configuration, such as high voltage supply, and watchdog enable/disable after reset are controlled via bit values in the non-volatile user options register (NVUSRO) register.

For a detailed description of the NVUSRO register, please refer to the device reference manual.

3.10.1 NVUSRO[PAD3V5V] field description

Table 19 shows how NVUSRO[PAD3V5V] controls the device configuration.

Table 19. PAD3V5V field description(1)

Value(2)	Description
0	High voltage supply is 5.0 V
1	High voltage supply is 3.3 V

1. See the device reference manual for more information on the NVUSRO register.
2. '1' is delivery value. It is part of shadow Flash, thus programmable by customer.

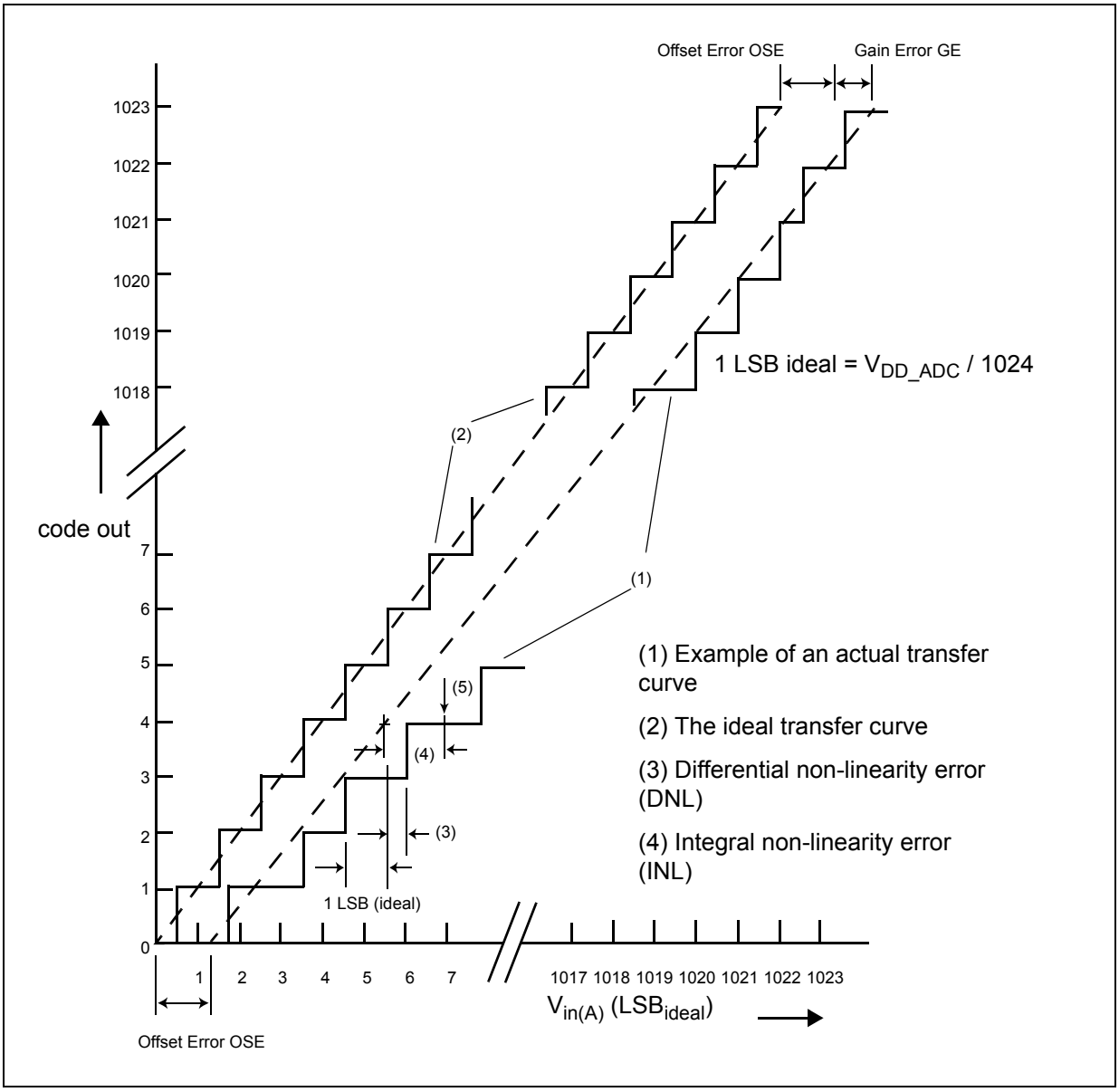
The DC electrical characteristics are dependent on the PAD3V5V bit value.

Table 24. Peripherals supply current (5 V and 3.3 V)(1)

Symbol		Parameter	Conditions		Value		Unit
					Typ	Max	
$I_{DD\_HV(CAN)}$	T	CAN (FlexCAN) supply current on VDD_HV_REG	500 Kbyte/s	Total (static + dynamic) consumption: – FlexCAN in loop-back mode – XTAL@ 8 MHz used as CAN engine clock source – Message sending period is 580 µs	21.6 * f_{periph}	28.1* f_{periph}	µA
$I_{DD\_HV(SCI)}$	T	SCI (LINFlex) supply current on VDD_HV_REG	Total (static + dynamic) consumption: – LIN mode – Baudrate: 115.2 Kbyte/s		10.8 * f_{periph}	14.1 * f_{periph}	
$I_{DD\_HV(SPI)}$	T	SPI (DSPI) supply current on VDD_HV_REG	Ballast dynamic consumption (continuous communication): – Baudrate: 2 Mbit/s – Transmission every 8 µs – Frame: 16 bits		4.8 * f_{periph}	6.3 * f_{periph}	
$I_{DD\_HV(ADC)}$	T	ADC supply current on VDD_HV_REG	VDD = 5.5 V	Ballast dynamic consumption (continuous conversion)	120 * f_{periph}	156 * f_{periph}	
$I_{DD\_HV\_ADC(ADC)}$	T	ADC supply current on VDD_HV_ADC	VDD = 5.5 V	Analog dynamic consumption (continuous conversion)	0.005 * f_{periph} + 2.8	0.007 * f_{periph} + 3.4	mA
$I_{DD\_HV(eTimer)}$	T	eTimer supply current on VDD_HV_REG	PWM signals generation on all 1 channel @10kHz	Dynamic consumption does not change varying the frequency	1.8	2.4	mA
$I_{DD\_HV(FlexRay)}$	T	FlexRay supply current on VDD_HV_REG	Static consumption		4.2 * f_{periph}	5.5 * f_{periph}	µA

1. Operating conditions: f_{periph} = 8 MHz to 64 MHz

Figure 15. ADC characteristics and error definitions



3.15.1 Input impedance and ADC accuracy

To preserve the accuracy of the A/D converter, it is necessary that analog input pins have low AC impedance. Placing a capacitor with good high-frequency characteristics at the input pin of the device can be effective: the capacitor should be as large as possible, ideally infinite. This capacitor contributes to attenuate the noise present on the input pin; further, it sources charge during the sampling phase, when the analog signal source is a high-impedance source.

A real filter can typically be obtained by using a series resistance with a capacitor on the input pin (simple RC filter). The RC filtering may be limited according to the source impedance value of the transducer or circuit supplying the analog signal to be measured.

3. The maximum program and erase times occur after the specified number of program/erase cycles. These maximum values are characterized but not guaranteed.
4. Actual hardware programming times. This does not include software overhead.
5. Typical bank programming time assumes that all cells are programmed in a single pulse. In reality some cells will require more than one pulse, adding a small overhead to total bank programming time (see Initial Max column).
6. Time between erase suspend resume and next erase suspend.

Table 34. Flash memory module life

Symbol		Parameter	Conditions	Value		Unit
				Min	Typ	
P/E	C	Number of program/erase cycles per block for 16 KB blocks over the operating temperature range (T_J)	—	100000	100000	cycles
P/E	C	Number of program/erase cycles per block for 32 KB blocks over the operating temperature range (T_J)	—	10000	100000	cycles
P/E	C	Number of program/erase cycles per block for 64 KB blocks over the operating temperature range (T_J)	—	10000	100000	cycles
P/E	C	Number of program/erase cycles per block for 128 KB blocks over the operating temperature range (T_J)	—	1000	100000	cycles
Retention	C	Minimum data retention at 85 °C average ambient temperature(1)	Blocks with 0 – 1000 P/E cycles	20	—	years
			Blocks with 10000 P/E cycles	10	—	years
			Blocks with 100000 P/E cycles	5	—	years

1. Ambient temperature averaged over duration of application, not to exceed recommended product operating temperature range.

Table 35. Flash read access timing

Symbol	C	Parameter	Conditions(1)	Max	Unit
Fmax	C	Maximum working frequency for Code Flash at given number of WS in worst conditions	2 wait states	66	MHz
			0 wait states	22	
Fmax	C	Maximum working frequency for Data Flash at given number of WS in worst conditions	8 wait states	66	MHz

1. VDD = 3.3 V ± 10% / 5.0 V ± 10%, TA = –40 to 125 °C, unless otherwise specified.

3.17 AC specifications

3.17.1 Pad AC specifications

Table 36. Output pin transition times

Symbol		C	Parameter	Conditions[1]		Value			Unit
						Min	Typ	Max	
T_{tr}	CC	D	Output transition time output pin[2] SLOW configuration	C_L = 25 pF	V_{DD} = 5.0 V ± 10%, PAD3V5V = 0	—	—	50	ns
		T		C_L = 50 pF		—	—	100	
		D		C_L = 100 pF		—	—	125	
		D		C_L = 25 pF	V_{DD} = 3.3 V ± 10%, PAD3V5V = 1	—	—	40	
		T		C_L = 50 pF		—	—	50	
		D		C_L = 100 pF		—	—	75	
T_{tr}	CC	D	Output transition time output pin[2] MEDIUM configuration	C_L = 25 pF	V_{DD} = 5.0 V ± 10%, PAD3V5V = 0 SIUL.PCRx.SRC = 1	—	—	10	ns
		T		C_L = 50 pF		—	—	20	
		D		C_L = 100 pF		—	—	40	
		D		C_L = 25 pF	V_{DD} = 3.3 V ± 10%, PAD3V5V = 1 SIUL.PCRx.SRC = 1	—	—	12	
		T		C_L = 50 pF		—	—	25	
		D		C_L = 100 pF		—	—	40	
T_{tr}	CC	D	Output transition time output pin[2] FAST configuration	C_L = 25 pF	V_{DD} = 5.0 V ± 10%, PAD3V5V = 0 SIUL.PCRx.SRC = 1	—	—	4	ns
				C_L = 50 pF		—	—	6	
				C_L = 100 pF		—	—	12	
				C_L = 25 pF	V_{DD} = 3.3 V ± 10%, PAD3V5V = 1 SIUL.PCRx.SRC = 1	—	—	4	
				C_L = 50 pF		—	—	7	
				C_L = 100 pF		—	—	12	
T_{sim}[3]	CC	T	Symmetric, same drive strength between N and P transistor	V_{DD} = 5.0 V ± 10%, PAD3V5V = 0		—	—	4	ns
				V_{DD} = 3.3 V ± 10%, PAD3V5V = 1		—	—	5	

1. V_{DD} = 3.3 V ± 10% / 5.0 V ± 10%, T_A = –40 °C to $T_{A\ MAX}$, unless otherwise specified.
2. C_L includes device and package capacitances (C_{PKG} < 5 pF).
3. Transition timing of both positive and negative slopes will differ maximum 50 %.

3.18 AC timing characteristics

3.18.1 $\overline{\text{RESET}}$ pin characteristics

The SPC56xP54x/SPC56xP60x implements a dedicated bidirectional RESET pin.

3.18.2 IEEE 1149.1 interface timing

Table 38. JTAG pin AC electrical characteristics

No.	Symbol		C	Parameter	Conditions	Min	Max	Unit
1	t_{JCYC}	CC	D	TCK cycle time	—	100	—	ns
2	t_{JDC}	CC	D	TCK clock pulse width (measured at $V_{DD\_HV\_IOx}/2$)	—	40	60	ns
3	$t_{TCKRISE}$	CC	D	TCK rise and fall times (40% – 70%)	—	—	3	ns
4	t_{TMSS}, t_{TDIS}	CC	D	TMS, TDI data setup time	—	5	—	ns
5	t_{TMSH}, t_{TDIH}	CC	D	TMS, TDI data hold time	—	25	—	ns
6	t_{TDOV}	CC	D	TCK low to TDO data valid	—	—	40	ns
7	t_{TDOI}	CC	D	TCK low to TDO data invalid	—	0	—	ns
8	t_{TDOHZ}	CC	D	TCK low to TDO high impedance	—	40	—	ns
9	t_{BSDV}	CC	D	TCK falling edge to output valid	—	—	50	ns
10	t_{BSDVZ}	CC	D	TCK falling edge to output valid out of high impedance	—	—	50	ns
11	t_{BSDHZ}	CC	D	TCK falling edge to output high impedance	—	—	50	ns
12	t_{BSDST}	CC	D	Boundary scan input valid to TCK rising edge	—	50	—	ns
13	t_{BSDHT}	CC	D	TCK rising edge to boundary scan input invalid	—	50	—	ns

Figure 22. JTAG test clock input timing

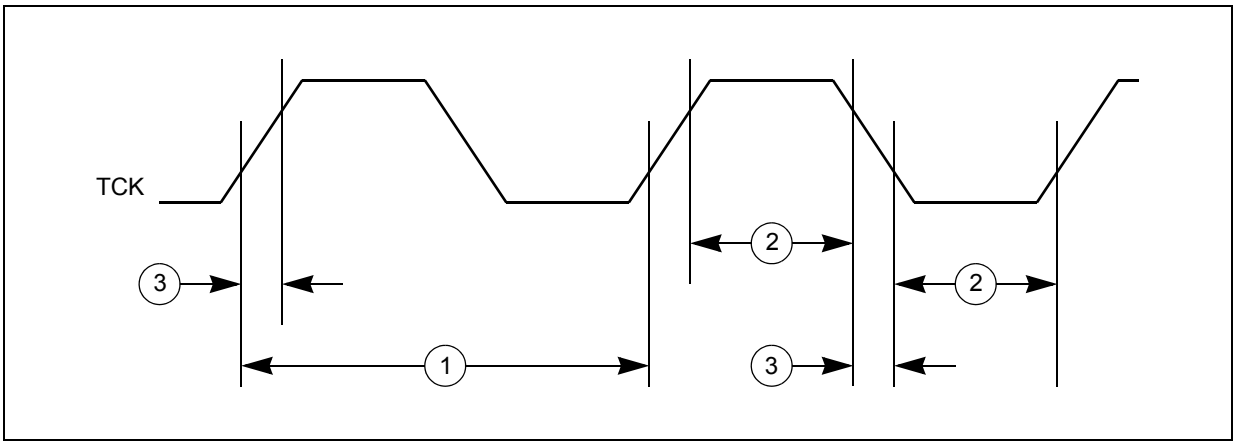
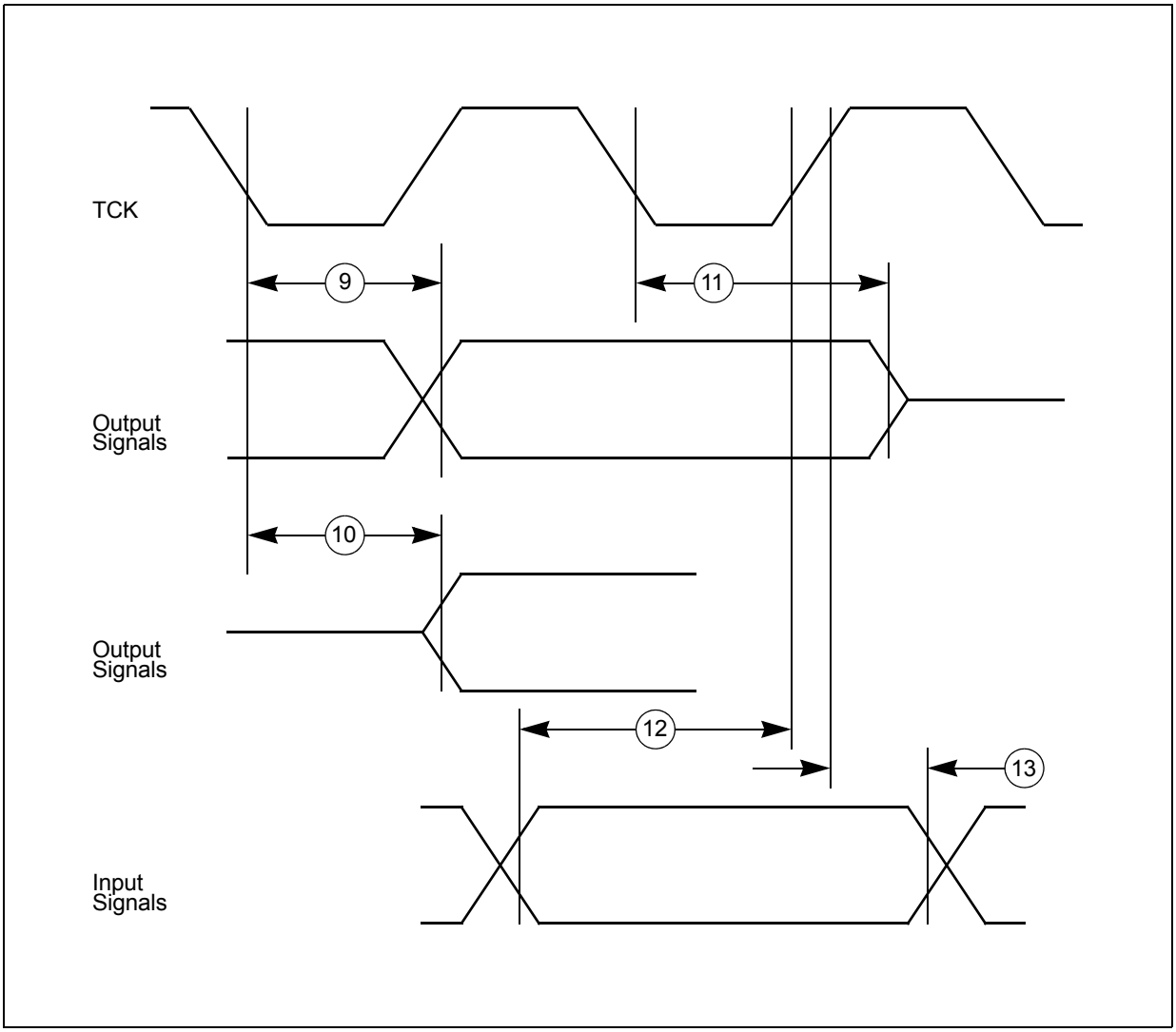


Figure 24. JTAG boundary scan timing



3.18.3 Nexus timing

Table 39. Nexus debug port timing(1)

No.	Symbol		C	Parameter	Value			Unit
					Min	Typ	Max	
1	t_{MCYC}	CC	D	MCKO cycle time	32	—	—	ns
2	t_{MDOV}	CC	D	MCKO edge to MDO data valid	–0.1 × t_{MCYC}	—	0.25 × t_{MCYC}	ns
3	t_{MSEOV}	CC	D	MCKO edge to $\overline{\text{MSEO}}$ data valid	–0.1 × t_{MCYC}	—	0.25 × t_{MCYC}	ns
4	t_{EVTOV}	CC	D	MCKO edge to $\overline{\text{EVTO}}$ data valid	–0.1 × t_{MCYC}	—	0.25 × t_{MCYC}	ns
5	t_{TCYC}	CC	D	TCK cycle time	64(2)	—	—	ns

Figure 30. DSPI classic SPI timing — master, CPHA = 1

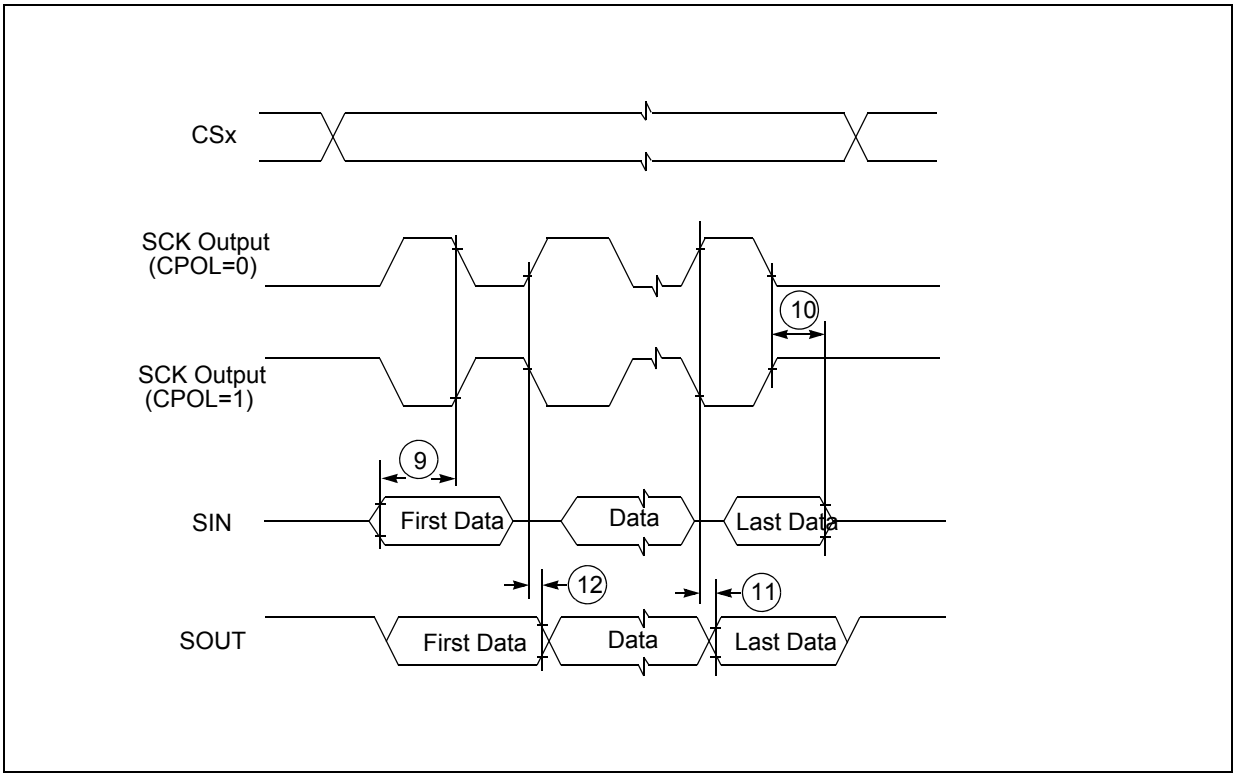
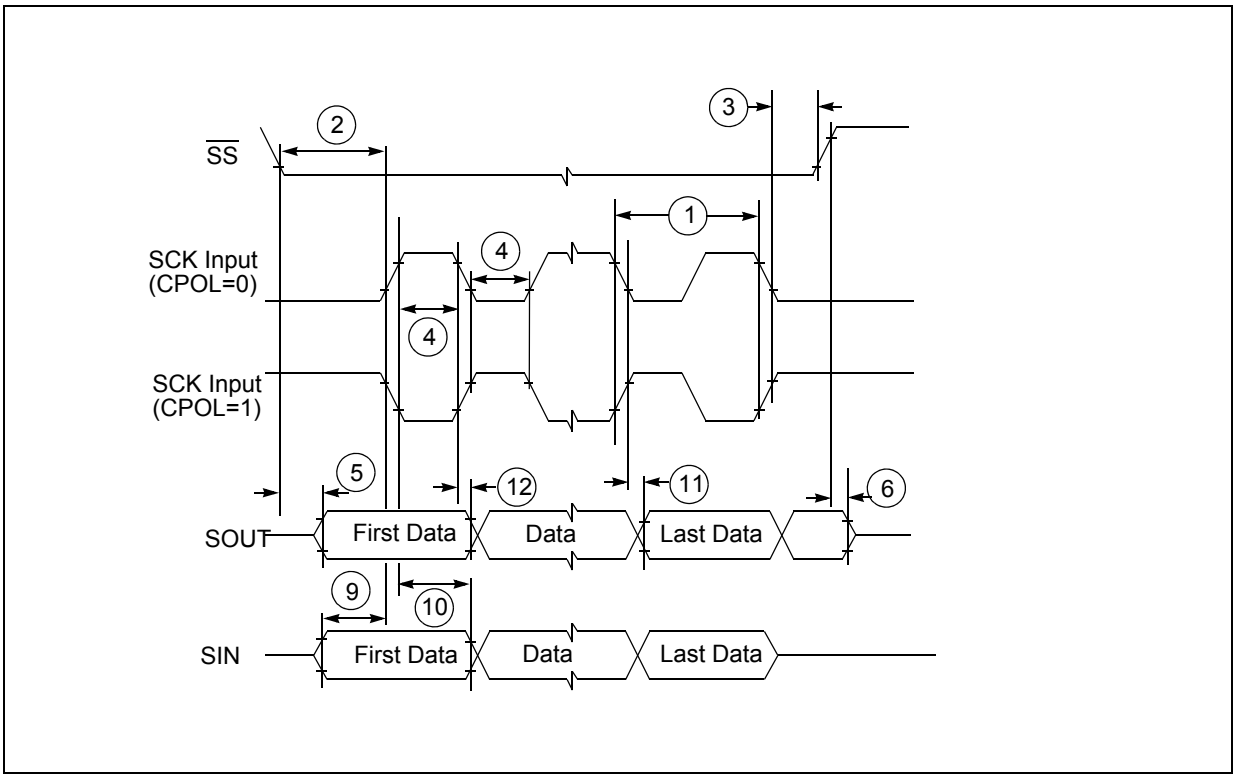


Figure 31. DSPI classic SPI timing — slave, CPHA = 0



4 Package characteristics

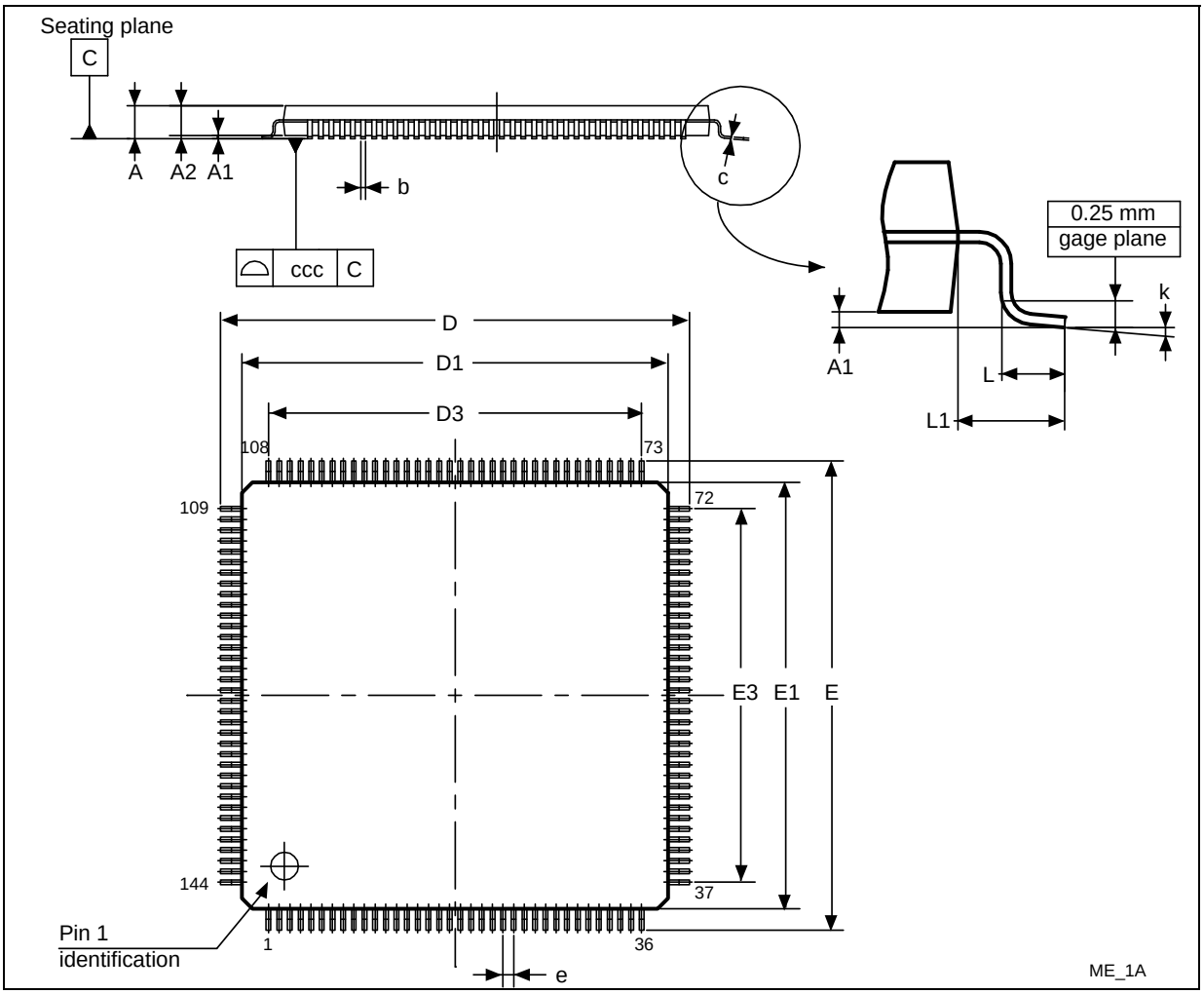
4.1 ECOPACK®

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: *www.st.com*. ECOPACK® is an ST trademark.

4.2 Package mechanical data

4.2.1 LQFP144 mechanical outline drawing

Figure 38. LQFP144 package mechanical drawing



4.2.2 LQFP100 mechanical outline drawing

Figure 39. LQFP100 package mechanical drawing

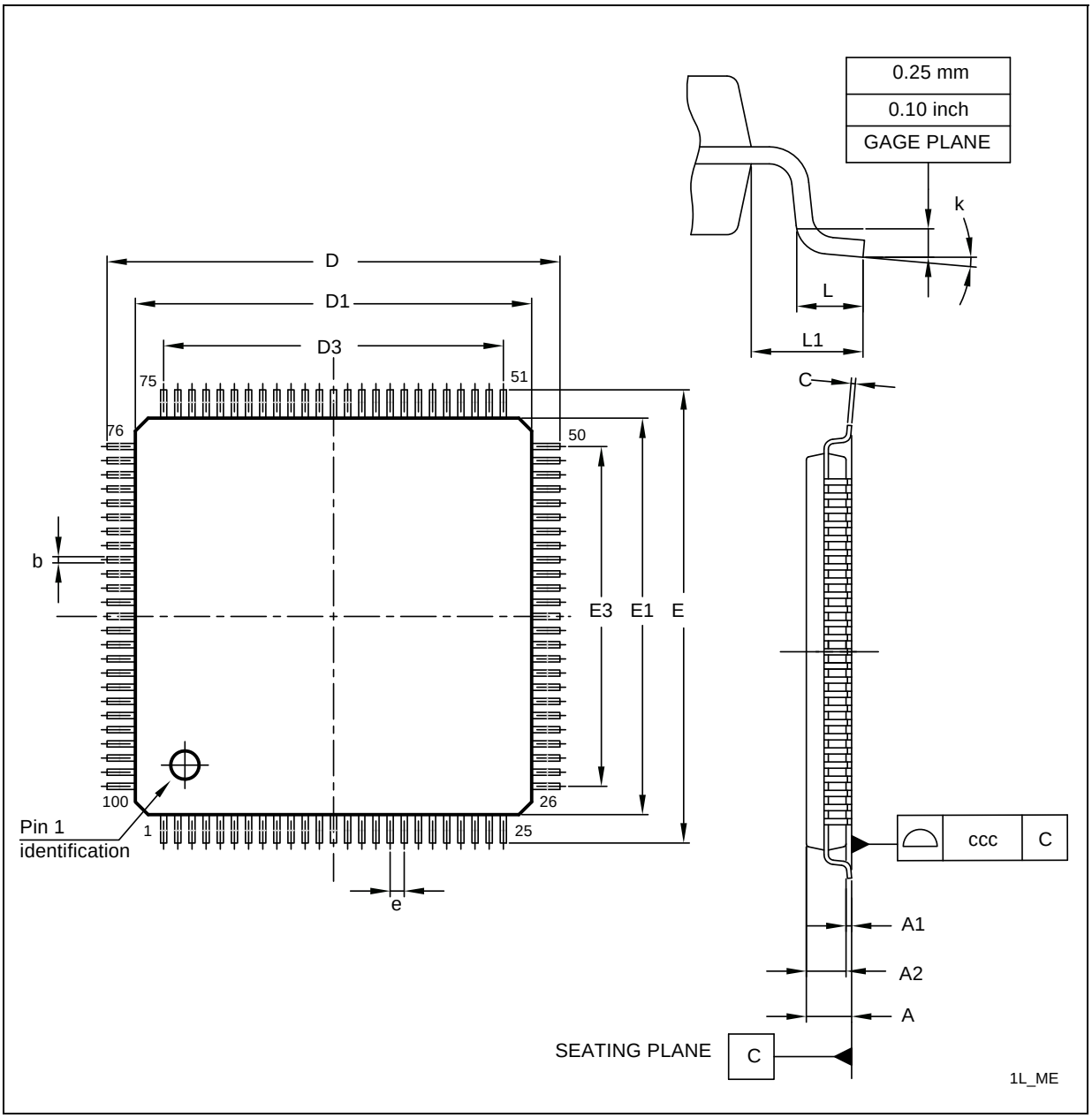


Table 43. LQFP100 mechanical data

Symbol	mm			inches[1]		
	Min	Typ	Max	Min	Typ	Max
A	—	—	1.600	—	—	0.0630
A1	0.050	—	0.150	0.0020	—	0.0059
A2	1.350	1.400	1.450	0.0531	0.0551	0.0571